



PATENT  
0808-0347P

Applicant:	Heon-Sang LEE et al.	Conf.:	1179
Appl. No.:	10/775,147	Group:	1713
Filed:	February 11, 2004	Examiner:	WILLIAM K. CHEUNG
For:	HEAT ABSORB-RELEASE PLASTIC RESIN COMPOSITION AND MOLDED PRODUCT THEREOF		

February 9, 2005

Transmitted herewith is a reply in the above-identified application.

- ☐ The enclosed document is being transmitted via the Certificate of Mailing provisions of 37 C.F.R. § 1.8.
- ☐ The enclosed document is being transmitted via facsimile.

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR		PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	13	-	20	=	0	\$50	\$0.00
INDEPENDENT	2	-	3	=	0	\$200	\$0.00
<input type="checkbox"/> FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM						\$360	\$0.00
						TOTAL	\$0.00

- ☒ Petition for one (1) month(s) extension of time pursuant to 37 C.F.R. §§ 1.17 and 1.136(a). \$120.00 for the extension of time.
- ☐ No fee is required.
- ☒ Check(s) in the amount of \$120.00 is(are) enclosed.
- ☐ Please charge Deposit Account No. 02-2448 in the amount of \$0.00. This form is submitted in triplicate.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. §§1.16 or 1.17; particularly, extension of time fees.

Respectfully submitted,

BIRCH, STEWART, KOLASCH & BIRCH, LLP

By  #42.874  
for James T. Eller, Jr., #39,538

JTE/CAM:cms  
0808-0347P

P.O. Box 747  
Falls Church, VA 22040-0747  
(703) 205-8000

Attachment(s)



MS AF  
REPLY UNDER  
37 C.F.R. § 1.116  
EXPEDITED PROCEDURE

EXAMINING GROUP 1713

PATENT  
0808-0347P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Heon-Sang LEE et al. Conf.: 1179  
Appl. No.: 10/775,147 Group: 1713  
Filed: February 11, 2004 Examiner: Cheung, William  
For: HEAT ABSORB-RELEASE PLASTIC RESIN  
COMPOSITION AND MOLDED PRODUCT THEREOF

REPLY UNDER 37 C.F.R. § 1.116

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

February 9, 2005

Sir:

In reply to the outstanding Office Action dated October 28, 2004, the period for replying having been extended one (1) month to February 28, 2005, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes: Amendments to the Specification; and  
Remarks.

02/10/2005 SDENBOB1 00000049 10775147

01 FC:1251

120.00 0P